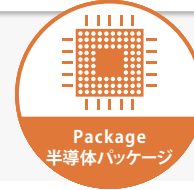


For high heat resistance power devices semiconductor encapsulation materials パワーデバイス用 高耐熱半導体封止材



Applications 用途

Power devices used in industry/Automotive inverters
産業・車載インバータなどで使用されるパワーデバイス



By adopting a new epoxy system, this material has excellent heat resistance and can be applied to the next generation power devices (SiC, GaN).

Contribute to improving power module performance and reliability under high temperature environment.

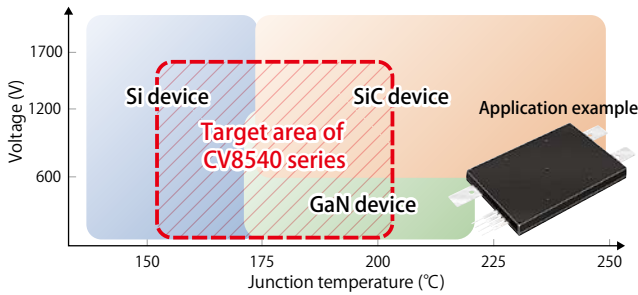
新規エポキシ樹脂システムの採用によって優れた耐熱性を持ち、次世代パワーデバイス (SiC, GaN) にも対応します。高温環境下におけるパワーモジュールの性能・信頼性向上に貢献します。

High heat resistance
高耐熱性

Low warpage, Low stress
低反り・低応力

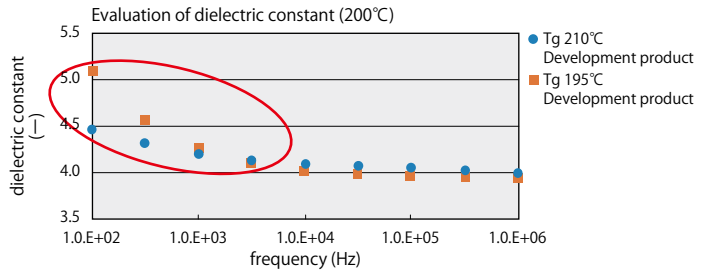
High insulation
高絶縁性

Concept コンセプト



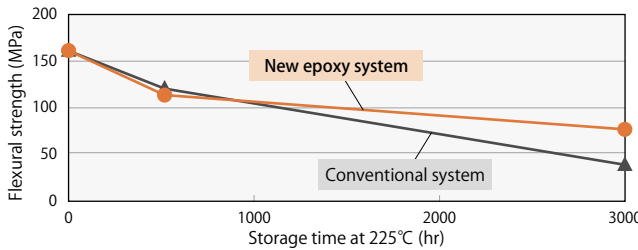
Dielectric property (Tg dependence) 誘電特性 (Tg依存性)

● Effective for high-temperature low dielectric constant and low dissipation factor

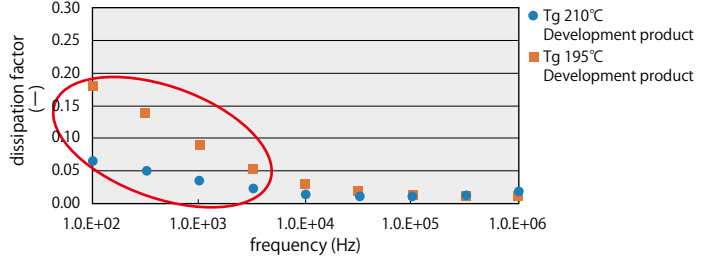


High heat resistance 高耐熱性

● Change in flexural strength by storage time at 225°C.



Evaluation of dissipation factor (200°C)



General properties 一般特性

Item	Unit	CV8540 series	
		Middle CTE & Low modulus type	Low CTE & Low modulus type
Feature	—	Middle CTE & Low modulus type	Low CTE & Low modulus type
C.T.E. ($\alpha 1/\alpha 2$)	ppm/°C	14/65	11/60
Tg (TMA)	°C	210	210
Flexural strength (RT/260°C)	MPa	110/23	100/21
Flexural modulus (RT/260°C)	GPa	13/1.0	13/1.0
Cure condition	—	175°C/100-150sec	
Post mold cure	—	175-200°C/4-8hr (200°C/4hr for above properties)	
UL flammability	UL-94	V-0	V-0

The written property values are just an example of our product line-up. Please contact us for details. 特性値はラインアップ中の一例であり、詳細はお問合せください。